

In re patent application of: Chuan Hu and Daoqiang Lu
Serial No. Not yet assigned
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U.S. PATENT DOCUMENTS

<u>Exam</u>	<u>Document</u>	<u>Issue</u>	<u>Name</u>	<u>Sub</u>	<u>Class</u>	<u>Sub</u>	<u>Class</u>
<u>Init</u>	<u>Number</u>	<u>Date</u>	<u>Name</u>				
<i>DH</i>	6,471,115 B1	10/29/2002	Ijuin et al.				
<i>DH</i>	6,495,397 B2	12/17/2002	Kubota et al.				

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FOREIGN PATENT DOCUMENTS

<u>Exam</u>	<u>Ref</u>	<u>Document</u>	<u>Publication</u>	<u>Country</u>	<u>Name</u>
<u>Init</u>		<u>Number</u>	<u>Date</u>		
<i>DH</i>	<i>DH</i>				
<i>DH</i>	<i>DH</i>				

OTHER DOCUMENTS

<u>Exam</u>	<u>Ref</u>	<u>Author, Title, Date, Pertinent Pages, Etc.)</u>
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<i>DH</i>	<i>DH</i>	Dodd et al., "Impact of Substrate Thickness on Single-Event Effects in Integrated Circuits," <i>IEEE Transactions on Nuclear Science</i> , Vol. 48, No. 6, p. 1865-1871 (December 2001).
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<i>DH</i>	<i>DH</i>	"Mechanical Enabling for the Intel® Pentium® 4 Processor in the 478-Pin Package," <i>Intel Corporation</i> (October 2001).

Examiner: *Dongh k. Jin*

Date Considered: 1/22/05